

**IN THE SPECIFICATION:**

Kindly amend the specification as follows:

**Please replace the paragraph beginning on line 27 of page 1 of the specification with the following new paragraph.**

However, machining holes using a laser device fitted with a Q switch providing trains of pulses of very short length, within the nanosecond range, raises problems of efficiency for machining holes. Indeed, machining holes, particularly of a certain depth, requires a large number of such successive pulses, which limits the machining speed for such holes and thus the industrial yield of such machining. Moreover, this type of laser device is relatively inflexible since it does not ~~enables~~enable the profile of the pulses generated by the resonator to be varied to obtain pulses with an intensity profile suited to machining each different type of hole. The machined hole geometry is thus difficult to vary due to the lack of adjustment flexibility of the parameters defining the very short pulses generated by the resonator. Further, holes of a relatively large diameter cannot be machined with pulses in the nanosecond range without using a machining method requiring drilling several holes along a circular outline. Finally, the Q switch frequency is limited because of the formation of a plasma during a short period, the plasma absorbing the luminous energy from a following pulse if it is still present above the hole machining area.

**Please replace the paragraph beginning on line 23 of page 2 of the specification with the following new paragraph.**

Owing to the features of the laser machining device according to the invention, it is possible to pierce holes efficiently and with great precision, i.e. with low machining tolerances, in fuel injection device components, for example in an injection nozzle or a

throttling orifice used for determining the flow rate of a fluid. This device enables primary pulses of relatively long length to be generated, in particular greater than 50  $\mu$ s. It has been observed that a train of pulses each with a relatively short length, for example between 1 and 20  $\mu$ s, increases the drilling yield and precision by means of a laser device. However, this efficiency decreases with periodic pulses in the nanosecond range generated by a resonator with a Q switch. In fact, it has been observed within the scope of the present invention that the machining yield for hard materials is lower in the nanosecond range than in the microsecond range. However, the machining precision requires that the energy per pulse must not be increased too much. The device according to the invention generates a second pulse train of this type with an optimum intensity profile owing to the modulation means provided downstream of a laser resonator without a Q switch supplying primary pulses whose energy is greater than that of a secondary pulse. The laser device is thus arranged to provide, in relatively short periods, a relatively large quantity of energy for quickly machining holes while modulating the luminous intensity to obtain precise and clean drilling. Another advantage of the modulated pulses is the ~~optimisation~~optimization of the drilling method relative to the dynamics of the plasma generated by the laser pulses. The primary pulses can be periodically supplied for machining a plurality of holes with a high industrial yield.

**Please replace the paragraph beginning on line 8 of page 3 of the specification with the following new paragraph.**

The modulation means are for example formed by a Pockels cell. Such cells can be controlled precisely and can also cause the secondary pulse train intensity profile to vary at the output of the cell to ~~optimise~~optimize the hole drilling efficiency depending on the material in which the holes are made and also depending on geometrical parameters defined for the holes.